



## Material Content Data Sheet



<b>Sales Product Name</b>		BGA 748L16 E6327		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA001129930						
<b>Package</b>		PG-TSLP-16-1		<b>Weight*</b>		7.31 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.268	3.67	3.67	36667	36667
leadframe	non noble metal	nickel	7440-02-0	2.483	33.98	33.98	339847	339847
wire	noble metal	gold	7440-57-5	0.099	1.36	1.36	13600	13600
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.002	0.03		273	
	organic material	carbon black	1333-86-4	0.040	0.55		5457	
	plastics	epoxy resin	-	0.538	7.37		73667	
encapsulation	inorganic material	silicondioxide	60676-86-0	3.407	46.62	54.57	466281	545678
	noble metal	gold	7440-57-5	0.131	1.79	1.79	17945	17945
plating	noble metal	silver	7440-22-4	0.214	2.93	2.93	29304	29304
glue	plastics	epoxy resin	-	0.025	0.34		3392	
	noble metal	silver	7440-22-4	0.099	1.36	1.70	13567	16959
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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